

ABSTRACT OF THE DISCLOSURE

A method and apparatus for removing degraded organics from an electroplating solution by passing at least a portion of electroplating solution through a filter. The apparatus generally includes a deposition cell including a fluid inlet, a fluid reservoir, and at least one filter disposed between the reservoir and the fluid inlet. The apparatus may further include a control valve disposed between the fluid reservoir and the fluid inlet for passing at least a portion of an electroplating solution to a recovery stream including the at least one filter. ~~Embodiments of the invention~~ ^{the} ~~further include a~~ ^{includes} ~~method generally including~~ the steps of providing a substrate having a seed layer disposed on a surface thereof, disposing the substrate in an electroplating solution, flowing a portion of the electroplating solution through a filter in an amount sufficient to remove an amount of organic additives from the electroplating solution equal to a calculated rate of organic additive degradation, and flowing the electroplating solution to the substrate.